

| L Number | Hits | Search Text   | DB  | Time stamp          |
|----------|------|---|---|---------------------|
| -        | 1    | (electrolytic near4 plating) and (feeder adj film)  | USPAT; US-PGPUB                             | 2003/11/28<br>12:46 |
| -        | 3227 | (electrolytic near4 plating) and substrate  | USPAT; US-PGPUB                             | 2002/11/22<br>11:07 |
| -        | 4669 | electrolytic near4 plating  | USPAT; US-PGPUB                             | 2002/11/22<br>13:52 |
| -        | 3142 | electrolytic adj plating  | USPAT; US-PGPUB                             | 2002/11/22<br>13:52 |
| -        | 3142 | electrolytic adj plating  | USPAT; US-PGPUB                             | 2002/11/22<br>13:52 |
| -        | 2452 | (electrolytic adj plating ) and (substrate or semiconductor)                                      | USPAT; US-PGPUB                             | 2002/11/22<br>13:53 |
| -        | 37   | tonami.in.  | USPAT; US-PGPUB                             | 2002/11/22<br>14:06 |
| -        | 3    | tonami.in. and Yoshiyuki  | USPAT; US-PGPUB                             | 2002/11/22<br>14:06 |
| -        | 37   | tonami.in.  | USPAT; US-PGPUB                             | 2002/11/22<br>14:06 |
| -        | 485  | tonami.in.  | JPO; DERWENT                                | 2002/11/22<br>14:06 |
| -        | 0    | tonami.in. and yoshiyuki  | JPO; DERWENT                                | 2002/11/22<br>14:07 |
| -        | 34   | tonami.in. and yoshiyuki  | JPO; DERWENT                                | 2002/11/22<br>14:13 |
| -        | 2143 | 216/13.cccls. or 216/18.cccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>14:15 |
| -        | 23   | (216/13.cccls. or 216/18.cccls.) and 216/40.cccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>14:15 |
| -        | 1    | ((216/13.cccls. or 216/18.cccls.) and 216/40.cccls.) and 216/100.cccls.                           | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>14:16 |
| -        | 147  | (216/13.cccls. or 216/18.cccls.) and 205/\$.cccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>14:16 |
| -        | 0    | ((216/13.cccls. or 216/18.cccls.) and 205/\$.cccls.) and 216/40.cccls.                            | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>14:16 |
| -        | 11   | ((216/13.cccls. or 216/18.cccls.) and 205/\$.cccls.) and 216/100.cccls.                           | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>14:18 |
| -        | 35   | (205/80.cccls. or 205/123.cccls. or 205/125.cccls. or 205/223.cccls.) and taper\$4                | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>14:19 |
| -        | 1    | ((205/80.cccls. or 205/123.cccls. or 205/125.cccls. or 205/223.cccls.) and taper\$4) and lift-off | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/22<br>15:37 |
| -        | 118  | 205/80.cccls.   | USPAT; US-PGPUB                             | 2002/11/22<br>15:09 |
| -        | 121  | 205/169.cccls.  | USPAT; US-PGPUB                             | 2002/11/22<br>15:10 |

|  |       |  |                    |                     |
|--|-------|--|--------------------|---------------------|
|  | 0     | (205/80, 123, 157, "169" and "223").ccls.<br>and (electrolytic adj plating adj<br>electrode)   | USPAT;<br>US-PGPUB | 2002/11/22<br>15:40 |
|  | 0     | (205/80,123,157,169,223).ccls. and<br>(electrolytic adj plating adj electrode)   | USPAT;<br>US-PGPUB | 2002/11/22<br>15:41 |
|  | 0     | c25d005/\$.ipc. and (electrolytic near4<br>plating) and (feeder adj film)  | JPO;<br>DERWENT    | 2002/11/22<br>16:46 |
|  | 0     | c25d05/\$.ipc.   | JPO;<br>DERWENT    | 2002/11/22<br>16:45 |
|  | 18607 | c25d005/\$.ipc.  | JPO;<br>DERWENT    | 2002/11/22<br>16:45 |
|  | 0     | c25d005/\$.ipc. and (electrolytic near4<br>plating) and (feeder adj film)  | JPO;<br>DERWENT    | 2002/11/22<br>16:46 |
|  | 651   | c25d005/\$.ipc. and (electrolytic near4<br>plating)  | JPO;<br>DERWENT    | 2002/11/22<br>18:46 |
|  | 55    | (c25d005/\$.ipc. and (electrolytic near4<br>plating) ) and (feed\$2 or electrode or<br>wire\$4 or base) and (cu or copper or ti<br>or titanium)  | JPO;<br>DERWENT    | 2002/11/22<br>16:51 |
|  | 285   | (c25d005/\$.ipc. and (electrolytic near4<br>plating) ) and (feed\$2 or electrode or<br>wire\$4 or base or conduct\$4)  | JPO;<br>DERWENT    | 2002/11/22<br>17:38 |
|  | 28    | (c25d005/\$.ipc. and (electrolytic near4<br>plating) ) and (feed\$2 or electrode or<br>wire\$4 or base or conduct\$4) near7<br>(pattern or mask\$4)  | JPO;<br>DERWENT    | 2002/11/22<br>18:41 |
|  | 3874  | (205/\$ or 216/\$).ccls. and (feed\$4 or<br>electrode or wire\$4 or base or conduct\$4)<br>near7 (pattern or mask\$4)  | USPAT;<br>US-PGPUB | 2002/11/22<br>18:20 |
|  | 1492  | 205/\$.ccls. and (feed\$4 or electrode or<br>wire\$4 or base or conduct\$4) near7<br>(pattern or mask\$4)  | USPAT;<br>US-PGPUB | 2002/11/22<br>18:24 |
|  | 1410  | (205/\$.ccls. and (feed\$4 or electrode or<br>wire\$4 or base or conduct\$4) near7<br>(pattern or mask\$4) ) and @ad<20010117  | USPAT;<br>US-PGPUB | 2002/11/22<br>18:23 |
|  | 1297  | 205/\$.ccls. and (feed\$4 or electrode or<br>wire\$4 or base or conduct\$4) near7<br>(partial\$4)  | USPAT;<br>US-PGPUB | 2002/11/22<br>18:28 |
|  | 149   | (205/\$.ccls. and (feed\$4 or electrode or<br>wire\$4 or base or conduct\$4) near7<br>(partial\$4) ) and (wire\$4 near7 form\$8)   | USPAT;<br>US-PGPUB | 2002/11/22<br>18:32 |
|  | 168   | (205/\$.ccls. and (feed\$4 or electrode or<br>wire\$4 or base or conduct\$4) near7<br>(partial\$4) ) and (wir\$4 near7 form\$5)  | USPAT;<br>US-PGPUB | 2002/11/22<br>18:34 |
|  | 43    | (205/\$.ccls. and (feed\$4 or electrode or<br>wire\$4 or base or conduct\$4) near7<br>(partial\$4) ) and ((wire or wiring)<br>near7 (formation or pattern or<br>fabrication))  | USPAT;<br>US-PGPUB | 2002/11/27<br>09:52 |
|  | 1312  | (205/80,123,125,223,157).ccls.   | USPAT;<br>US-PGPUB | 2002/11/22<br>18:40 |
|  | 1868  | (216/13,18,40,100).ccls.   | USPAT;<br>US-PGPUB | 2002/11/22<br>18:41 |
|  | 3103  | ((205/80,123,125,223,157).ccls.) or<br>((216/13,18,40,100).ccls.)  | USPAT;<br>US-PGPUB | 2002/11/22<br>18:41 |
|  | 1015  | (((205/80,123,125,223,157).ccls.) or<br>((216/13,18,40,100).ccls.)) and (feed\$2<br>or electrode or wire\$4 or base or<br>conduct\$4) near7 (pattern or mask\$4 or<br>partial\$4)  | USPAT;<br>US-PGPUB | 2002/11/22<br>18:43 |
|  | 964   | ((((205/80,123,125,223,157).ccls.) or<br>((216/13,18,40,100).ccls.)) and (feed\$2<br>or electrode or wire\$4 or base or<br>conduct\$4) near7 (pattern or mask\$4 or<br>partial\$4) ) and @ad<20010117                                      | USPAT;<br>US-PGPUB | 2002/11/22<br>18:44 |
|  | 99    | ((((205/80,123,125,223,157).ccls.) or<br>((216/13,18,40,100).ccls.)) and (feed\$2<br>or electrode or wire\$4 or base or<br>conduct\$4) near7 (pattern or mask\$4 or<br>partial\$4) ) and @ad<20010117) and<br>(electrolytic near4 plating) | USPAT;<br>US-PGPUB | 2002/11/23<br>15:04 |

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|  | 99    | (((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4) ) and @ad<20010117) and (electrolytic near4 plating)  | USPAT;<br>US-PGPUB | 2002/11/23<br>11:59 |
|  | 99    | (((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4) ) and @ad<20010117) and (electrolytic near4 plating)  | USPAT;<br>US-PGPUB | 2002/11/26<br>18:55 |
|  | 1     | 4866008.pn.   | USPAT;<br>US-PGPUB | 2002/11/23<br>17:09 |
|  | 103   | 205/186.ccls.   | USPAT;<br>US-PGPUB | 2002/11/27<br>09:45 |
|  | 361   | (((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4) ) and @ad<20010117) and (electrolytic\$4 or electrodedeposit\$4)   | USPAT;<br>US-PGPUB | 2002/11/26<br>18:54 |
|  | 99    | (((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4) ) and @ad<20010117) and (electrolytic near4 plating)  | USPAT;<br>US-PGPUB | 2002/11/26<br>18:59 |
|  | 263   | (((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4) ) and @ad<20010117) and (electrolytic\$4 or electrodedeposit\$4)<br>not<br>((((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4) ) and @ad<20010117) and (electrolytic near4 plating) ) | USPAT;<br>US-PGPUB | 2002/11/26<br>18:56 |
|  | 270   | (205/186,123,125,223,157).ccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117 and ((electrolytic near plating) or electroplating or electrodedeposit\$4)  | USPAT;<br>US-PGPUB | 2002/11/27<br>10:42 |
|  | 19    | 205/186.ccls. and ((feed\$4 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (partial\$4 or mask or pattern) )  | USPAT;<br>US-PGPUB | 2002/11/27<br>10:34 |
|  | 3     | "2000008247"  | JPO;<br>DERWENT    | 2002/11/27<br>10:41 |
|  | 22685 | h011021/3205.ipc.   | JPO;<br>DERWENT    | 2002/11/27<br>10:41 |
|  | 47    | h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodedeposit\$4)   | JPO;<br>DERWENT    | 2002/11/27<br>15:48 |
|  | 1     | 04262536.pn.  | DERWENT            | 2002/11/27<br>14:29 |
|  | 1     | "04262536"  | DERWENT            | 2002/11/27<br>14:30 |
|  | 2     | "04262536"  | JPO;<br>DERWENT    | 2002/11/27<br>15:10 |
|  | 1     | 5550068.pn.   | USPAT;<br>US-PGPUB | 2002/11/27<br>15:10 |

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|  | 0    | (205/186,123,125,223,157). and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)   | USPAT;<br>US-PGPUB                                      | 2002/11/27<br>15:51 |
|  | 283  | (205/186,123,125,223,157).ccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)  | USPAT;<br>US-PGPUB                                      | 2002/11/27<br>15:56 |
|  | 384  | (h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)  | JPO;<br>DERWENT   | 2002/11/27<br>15:55 |
|  | 337  | ((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4))  | JPO;<br>DERWENT   | 2002/11/27<br>15:53 |
|  | 28   | ((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) and ((remove or etch) near7 (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed)) | JPO;<br>DERWENT   | 2002/11/27<br>16:18 |
|  | 1    | 5550068.pn.  | USPAT;<br>US-PGPUB                                      | 2002/11/27<br>16:18 |
|  | 5707 | yoshiyuki.in.  | USPAT;<br>US-PGPUB                                      | 2003/03/28<br>10:42 |
|  | 3    | yoshiyuki.in. and tonami   | USPAT;<br>US-PGPUB                                      | 2003/03/28<br>10:42 |
|  | 9026 | yoshihiro.in.  | USPAT;<br>US-PGPUB                                      | 2003/03/28<br>10:44 |
|  | 13   | yoshihiro.in. and koshido  | USPAT;<br>US-PGPUB                                      | 2003/03/28<br>10:44 |
|  | 15   | (yoshiyuki.in. and tonami) or (yoshihiro.in. and koshido)  | USPAT;<br>US-PGPUB                                      | 2003/03/28<br>10:44 |
|  | 154  | (205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$6) 205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.  | USPAT;<br>US-PGPUB                                      | 2003/03/31<br>16:39 |
|  | 1311 |  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/31<br>18:09 |
|  | 1    | 5550068.pn.  | USPAT;<br>US-PGPUB                                      | 2003/07/11<br>14:24 |
|  | 2    | "06260482"   | JPO;<br>DERWENT   | 2003/07/11<br>17:42 |
|  | 20   | (438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)   | JPO;<br>DERWENT   | 2003/07/11<br>17:50 |

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|--|------|--|--------------------|---------------------|
|  | 20   | ((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117  | JPO;<br>DERWENT    | 2003/07/11<br>17:50 |
|  | 509  | ((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4))   | USPAT;<br>US-PGPUB | 2003/07/11<br>17:49 |
|  | 0    | ((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117  | JPO;<br>DERWENT    | 2003/07/11<br>17:50 |
|  | 320  | ((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117  | USPAT;<br>US-PGPUB | 2003/07/11<br>17:50 |
|  | 223  | ((((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117) and tungsten  | USPAT;<br>US-PGPUB | 2003/07/11<br>17:50 |
|  | 0    | ((((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117) and (diffusion near3 prevent\$4 near3 tungsten)                               | JPO;<br>DERWENT    | 2003/07/11<br>17:51 |
|  | 9    | ((((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117) and (diffusion near3 prevent\$4 near3 tungsten))                              | USPAT;<br>US-PGPUB | 2003/07/12<br>10:07 |
|  | 1    | 5550068.pn.  | USPAT;<br>US-PGPUB | 2003/07/12<br>10:07 |
|  | 4974 | ((electro adj plating) or electroplating) same (gold or au)  | USPAT;             | 2003/11/28          |
|  | 6001 | ((electro adj plating) or electroplating) same (line or circuit)   | USPAT;<br>US-PGPUB | 12:49               |
|  | 1514 | ((((electro adj plating) or electroplating) same (gold or au)) and ((electro adj plating) or electroplating) same (line or circuit))                             | USPAT;<br>US-PGPUB | 2003/11/28<br>12:50 |
|  | 2803 | ((electro adj plating) or electroplating) with (gold or au)  | USPAT;<br>US-PGPUB | 2003/11/28<br>12:57 |
|  | 2956 | ((electro adj plating) or electroplating) with (line or circuit)   | USPAT;             | 2003/11/28          |
|  | 471  | ((((electro adj plating) or electroplating) with (gold or au)) and ((electro adj plating) or electroplating) with (line or circuit))                             | USPAT;<br>US-PGPUB | 12:53               |
|  | 140  | ((((electro adj plating) or electroplating) with (gold or au)) and ((electro adj plating) or electroplating) with (line or circuit))) and (diffusion or barrier) | USPAT;<br>US-PGPUB | 2003/11/28<br>12:52 |
|  | 2034 | ((electro adj plating) or electroplating) near7 (gold or au)   | USPAT;<br>US-PGPUB | 2003/11/28<br>12:53 |
|  | 1966 | ((electro adj plating) or electroplating) near7 (line or circuit)  | USPAT;<br>US-PGPUB | 2003/11/28<br>12:54 |
|  | 215  | ((((electro adj plating) or electroplating) near7 (gold or au)) and ((electro adj plating) or electroplating) near7 (line or circuit))                           | USPAT;<br>US-PGPUB | 2003/11/28<br>15:43 |
|  | 365  | (h011021/\$.ipc. or c23c016/\$.ipc.) and ((electro adj plating) or electroplating) and (gold or au)  | JPO;<br>DERWENT    | 2003/11/28<br>12:58 |
|  | 101  | (h011021/\$.ipc. or c23c016/\$.ipc.) and ((electro adj plating) or electroplating) and (gold or au) and (line or circuit)  | JPO;<br>DERWENT    | 2003/11/28<br>13:19 |
|  | 23   | ((h011021/\$.ipc. or c23c016/\$.ipc.) and ((electro adj plating) or electroplating) and (gold or au) and (line or circuit)) and (diffusion or adhesi\$4)         | JPO;<br>DERWENT    | 2003/11/28<br>13:21 |
|  | 15   | ((((electro adj plating) or electroplating) near7 (gold or au)) and ((electro adj plating) or electroplating) near7 (line or circuit))) and (wet near etch\$4)   | USPAT;<br>US-PGPUB | 2003/11/28<br>15:43 |

|   |    |   |                    |                     |
|---|----|---|--------------------|---------------------|
| - | 11 | ((((electro adj plating) or electroplating) near7 (gold or au)) and (((electro adj plating) or electroplating) near7 (line or circuit))) and (wet near etch\$4)) and @ad<20000117 | USPAT;<br>US-PGPUB | 2003/11/28<br>15:44 |
|---|----|---|--------------------|---------------------|